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ABSTRACT

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5 This invention provides a polishing medium for CMP, comprising an oxidizing agent, a metal-oxide-dissolving agent, a protective-film-forming agent, a water-soluble polymer, and water, and a polishing method making use of this polishing medium. Also, it is preferable that the water-soluble polymer has a weight-average molecular weight of 500 or more and the polishing medium has a 10 coefficient of kinetic friction of 0.25 or more, a Ubbelode's viscosity of from 0.95 cP to 1.5 cP and a point-of-inflection pressure of 50 gf/cm².